Designer's™ Data Sheet

Insulated Gate Bipolar Transistor with Anti-Parallel Diode

N-Channel Enhancement-Mode Silicon Gate

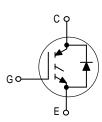
This Insulated Gate Bipolar Transistor (IGBT) is co-packaged with a soft recovery ultra-fast rectifier and uses an advanced termination scheme to provide an enhanced and reliable high voltage-blocking capability. Short circuit rated IGBT's are specifically suited for applications requiring a guaranteed short circuit withstand time such as Motor Control Drives. Fast switching characteristics result in efficient operations at high frequencies. Co-packaged IGBT's save space, reduce assembly time and cost.

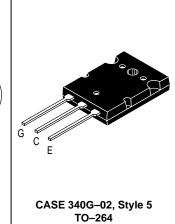
- Industry Standard High Power TO–264 Package (TO–3PBL)
- High Speed E_{Off}: 60 μJ per Amp typical at 125°C
- High Short Circuit Capability 10 μs minimum
- Soft Recovery Free Wheeling Diode is included in the package
- Robust High Voltage Termination
- Robust RBSOA

MGY40N60D

Motorola Preferred Device

IGBT & DIODE IN TO-264 40 A @ 90°C 66 A @ 25°C **600 VOLTS SHORT CIRCUIT RATED**





MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit	
Collector–Emitter Voltage	VCES	600	Vdc	
Collector–Gate Voltage (R _{GE} = 1.0 MΩ)	VCGR	600	Vdc	
Gate-Emitter Voltage — Continuous	V _{GE}	±20	Vdc	
Collector Current — Continuous @ T _C = 25°C — Continuous @ T _C = 90°C — Repetitive Pulsed Current (1)	I _{C25} I _{C90} I _{CM}	66 40 132	Adc Apk	
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	260 2.08	Watts W/°C	
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to 150	°C	
Short Circuit Withstand Time (V_{CC} = 360 Vdc, V_{GE} = 15 Vdc, T_J = 25°C, R_G = 20 Ω)	t _{SC}	10	μS	
Thermal Resistance — Junction to Case – IGBT — Junction to Case – Diode — Junction to Ambient	R _θ JC R _θ JC R _θ JA	0.48 1.13 35	°C/W	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C	
Mounting Torque, 6–32 or M3 screw	10	10 lbf•in (1.13 N•m)		

⁽¹⁾ Pulse width is limited by maximum junction temperature.

Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

Preferred devices are Motorola recommended choices for future use and best overall value



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ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector-to-Emitter Breakdown Voltage		BVCES	600			Vdc
(VGE = 0 Vdc, IC = 250 µAdc) Temperature Coefficient (Positive)			600 —	870	_	mV/°C
Zero Gate Voltage Collector Cur		ICES			400	μAdc
(VCE = 600 Vdc, VGE = 0 Vdc) (VCE = 600 Vdc, VGE = 0 Vdc, TJ = 125°C)				_	100 2500	
Gate–Body Leakage Current (V _{GE} = ± 20 Vdc, V _{CE} = 0 Vdc)		IGES	_	_	250	nAdc
ON CHARACTERISTICS (1)		•		•		•
Collector-to-Emitter On-State Voltage		VCE(on)				Vdc
$(V_{GE} = 15 \text{ Vdc}, I_{C} = 20 \text{ Adc})$	Fu = 125°C)			2.20 2.10	2.80	
$(V_{GE} = 15 \text{ Vdc, I}_{C} = 20 \text{ Adc, T}_{J} = 125^{\circ}\text{C})$ $(V_{GE} = 15 \text{ Vdc, I}_{C} = 40 \text{ Adc})$			_	2.60	3.25	
Gate Threshold Voltage		V _{GE(th)}				Vdc
(V _{CE} = V _{GE} , I _C = 1 mAdc) Threshold Temperature Coeffi	cient (Negative)		4.0	6.0 10	8.0	mV/°C
Forward Transconductance (VC		9fe	<u> </u>	12	<u> </u>	Mhos
DYNAMIC CHARACTERISTICS	E = 10 Vdc, 1C = 40 Adc)	91e		12		1411103
Input Capacitance		C _{ies}	I _	6810	Ι_	pF
Output Capacitance	(V _{CE} = 25 Vdc, V _{GE} = 0 Vdc,	C _{oes}	<u> </u>	464		1 "
Transfer Capacitance	f = 1.0 MHz)	C _{res}	<u> </u>	15		1
SWITCHING CHARACTERISTIC		eres		10		
Turn-On Delay Time		t _{d(on)}	I _	126		ns
Rise Time		t _r	<u> </u>	95	<u> </u>	- 1.0
Turn-Off Delay Time	(V _{CC} = 360 Vdc, I _C = 40 Adc,	<u> </u>	_	530		-
Fall Time	V _{GE} = 15 Vdc, L = 300 μH	t _d (off)	<u> </u>	180		1
Turn-Off Switching Loss	$R_G = 20 \Omega$, $T_J = 25^{\circ}C$) Energy losses include "tail"	E _{off}	<u> </u>	1.50	2.10	mJ
Turn–On Switching Loss	Energy losses include tall	-		2.30	2.10	1113
Total Switching Loss	-	Eon	\vdash	3.80		-
		E _{ts}				
Turn-On Delay Time	-	td(on)	_	113	_	ns
Rise Time		tr		104		_
Turn-Off Delay Time	V _{CC} = 360 Vdc, I _C = 40 Adc, V _{GE} = 15 Vdc, L = 300 μH	td(off)		588	_	-
Fall Time	$R_G = 20 \Omega, T_J = 125^{\circ}C)$	t _f		346		
Turn–Off Switching Loss	Energy losses include "tail"	E _{off}		2.70	_	mJ
Turn–On Switching Loss		E _{on}		3.80	_	
Total Switching Loss		E _{ts}	_	6.50	_	
Gate Charge	(Voo = 360 Vdo lo = 40 Ado	QT		248	_	nC
	$(V_{CC} = 360 \text{ Vdc}, I_{C} = 40 \text{ Adc}, V_{GE} = 15 \text{ Vdc})$	Q ₁		49	_]
		Q ₂	_	81	_	
DIODE CHARACTERISTICS						
Diode Forward Voltage Drop				1.40	1.70	Vdc
(I _{EC} = 20 Adc) (I _{EC} = 20 Adc, T _J = 125°C)				1.19 1.04	1.70	
(I _{EC} = 40 Adc)		_	1.36	2.00		

(1) Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

(continued)

ELECTRICAL CHARACTERISTICS — continued ($T_J = 25$ °C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTICS — conti	nued					
Reverse Recovery Time		t _{rr}	_	138	_	ns
	$(I_F = 40 \text{ Adc}, V_R = 360 \text{ Vdc},$	ta	_	78	_	
	dI _F /dt = 200 A/μs)	t _b	_	60	_	
Reverse Recovery Stored Charge		Q _{RR}	_	2.1	_	μС
Reverse Recovery Time		t _{rr}	_	213	_	ns
	$(I_F = 40 \text{ Adc}, V_R = 360 \text{ Vdc},$	ta		122	_	
	$dI_F/dt = 200 \text{ A/}\mu\text{s}, T_J = 125^{\circ}\text{C}$	t _b	_	91	_	
Reverse Recovery Stored Charge		Q _{RR}	_	4.9	_	μС
NTERNAL PACKAGE INDUCTANCE						
Internal Emitter Inductance (Measured from the emitter lead 0.25" from package to emitter bond pad)		LE	_	13	_	nH

TYPICAL ELECTRICAL CHARACTERISTICS

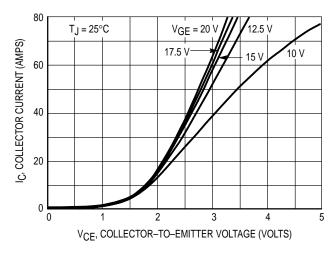


Figure 1. Output Characteristics, T_J = 25°C

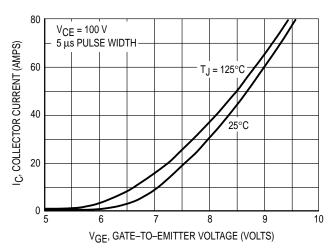


Figure 3. Transfer Characteristics

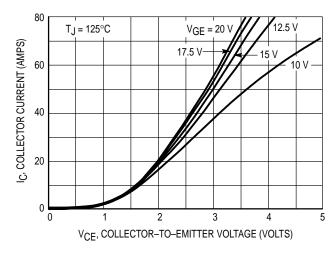


Figure 2. Output Characteristics, T_J = 125°C

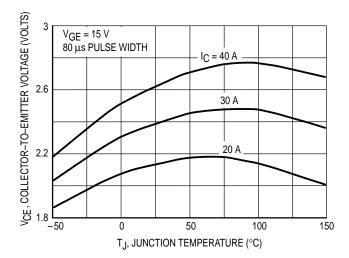


Figure 4. Collector–to–Emitter Saturation Voltage versus Junction Temperature

MGY40N60D

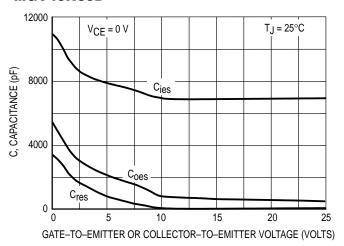


Figure 5. Capacitance Variation

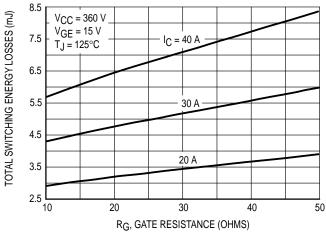


Figure 7. Total Switching Losses versus
Gate Resistance

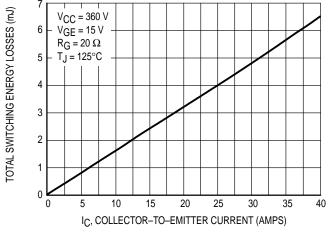


Figure 9. Total Switching Losses versus Collector-to-Emitter Current

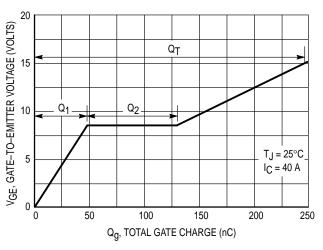


Figure 6. Gate-to-Emitter Voltage versus
Total Charge

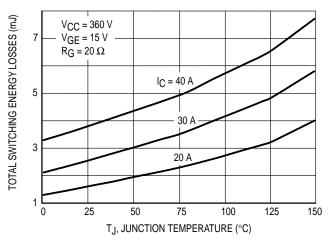


Figure 8. Total Switching Losses versus Junction Temperature

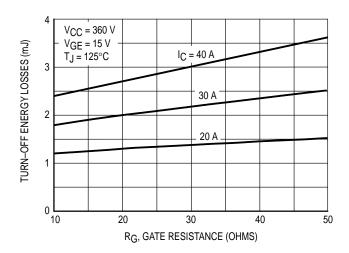


Figure 10. Turn-Off Losses versus
Gate Resistance

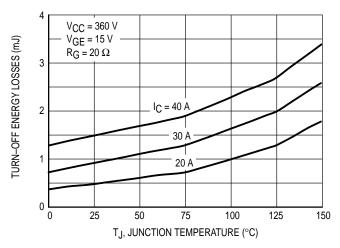
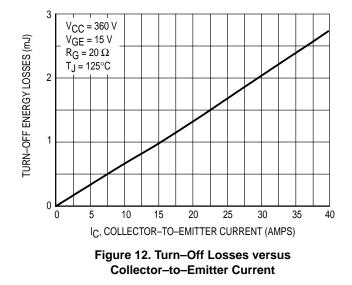


Figure 11. Turn-Off Losses versus Junction Temperature



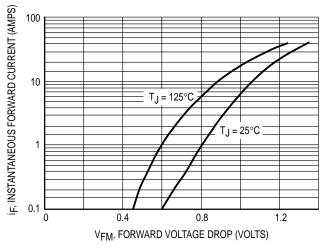


Figure 13. Typical Diode Forward Drop versus Instantaneous Forward Current

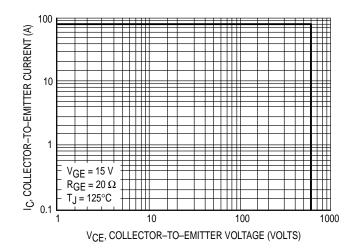
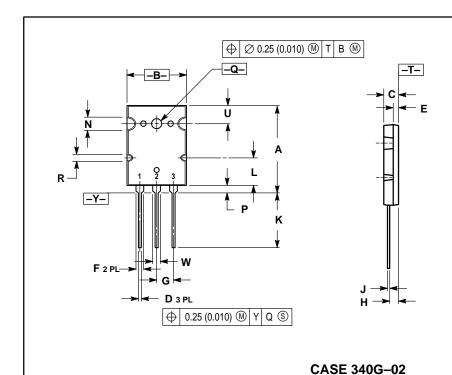


Figure 14. Reverse Biased Safe Operating Area

PACKAGE DIMENSIONS



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.8	2.9	1.102	1.142	
В	19.3	20.3	0.760	0.800	
C	4.7	5.3	0.185	0.209	
D	0.93	1.48	0.037	0.058	
Е	1.9	2.1	0.075	0.083	
F	2.2	2.4	0.087	0.102	
G	5.45 BSC		0.215 BSC		
Н	2.6	3.0	0.102	0.118	
J	0.43	0.78	0.017	0.031	
K	17.6	18.8	0.693	0.740	
L	11.0	11.4	0.433	0.449	
N	3.95	4.75	0.156	0.187	
Р	2.2	2.6	0.087	0.102	
Ø	3.1	3.5	0.122	0.137	
R	2.15	2.35	0.085	0.093	
C	6.1	6.5	0.240	0.256	
W	2.8	3.2	0.110	0.125	

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